PwrSoC 2023

High Performance Metal Chip Power Inductor for IVR

28.Sept.2023
TAIYO YUDEN Co., LTD.

Agenda

Introduction

Trend for Processor (CPU/GPU/AI) Package

Inductor proposal for Processor Package ~LSCN series metal type multi layer power inductor~

Summary

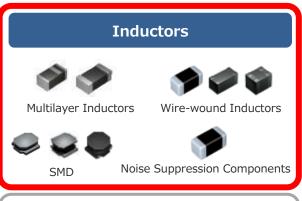
Corporate Overview

Corporate Name	TAIYO YUDEN CO., LTD.			
Head Office	Kyobashi East Bldg., 2-7-19, Kyobashi, Chuo-ku, Tokyo 104-0031, Japan			
Date of Establishment	March 23, 1950			
Representative Director, President and CEO	Katsuya Sase			
Capital	¥33,575 million (as of March 31, 2023)			
Net Sales	¥319,504million (Fiscal year ended March 2023/on consolidated basis)			
Number of Employees	21,819 (as of March 31, 2023/on consolidated basis)			
Main Business	Development, production and sales of electronic components			
Multilayer ceramic capacitors Inductors FBAR/SAW devices for mobile communications Circuit modules Aluminum electrolytic capacitors Power Storage Device				

TAIYO YUDEN

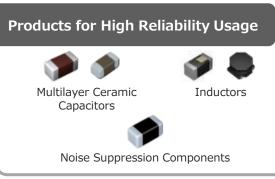
Products of TAIYO YUDEN







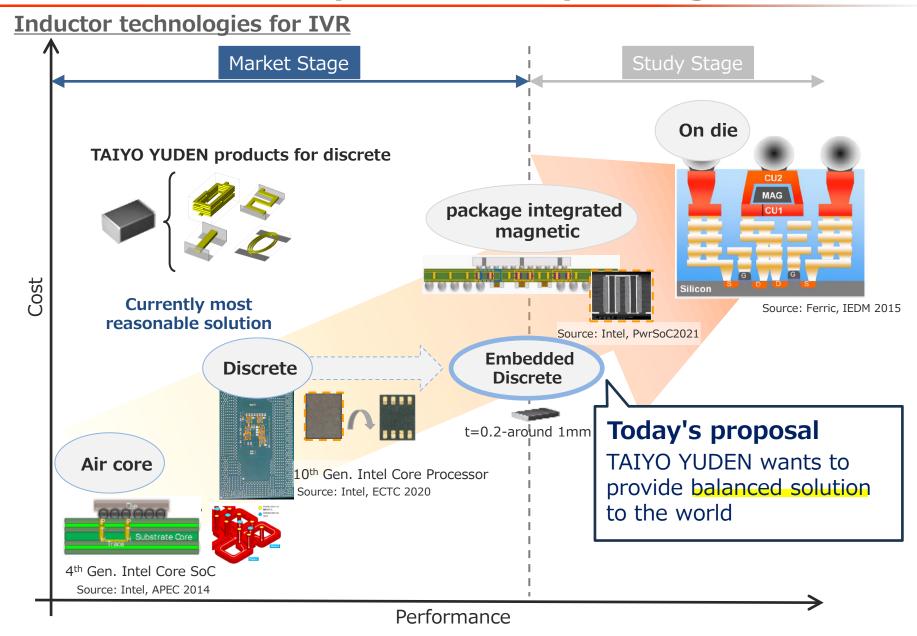






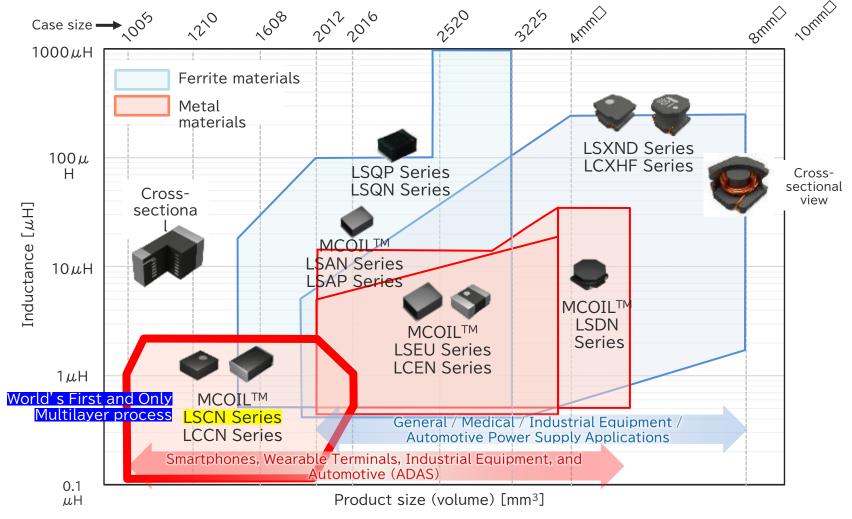


Trend for Processor (CPU/GPU/AI) Package



TAIYO YUDEN's Power inductor product line-up

Targeting a wide range of markets, from IoT device (wearables) and mobile equipment to high-reliability automotive and industrial equipment with optimum materials and structure (wire-wound or multilayer) design.



*MCOIL is a registered trademark or trademark of TAIYO YUDEN CO., LTD. in Japan and other countries.

The names of series noted in the text are excerpted from part numbers that indicate the types and characteristics of the products, and therefore are neither product names nor trademarks.

What's LSCN series? Metal base multilayer power Inductor

Ultra Small & Thin
Metal Power Inductor
for Miniaturization / Energy Saving

For example, Case Size **0402inch**Inductance **1.0µH**Saturation current **1.0A**

What's LSCN series?: Metal base multi layer power Inductor



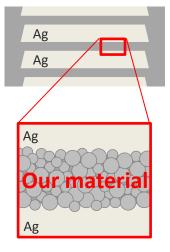
LSCN series use multi layer process & unique Metal material.

- High current with small package
- Small case size and low profile
- Customizability (e.g. flexibility in size and array like 2 in 1).

Basic structure of LSCN

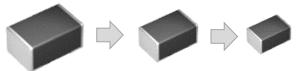
- First in the world -





Strong points for LSCN(MC)

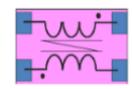
A). Further smaller size (<=1005mm)



B). Further lower profile (<=0.2-0.3mm)

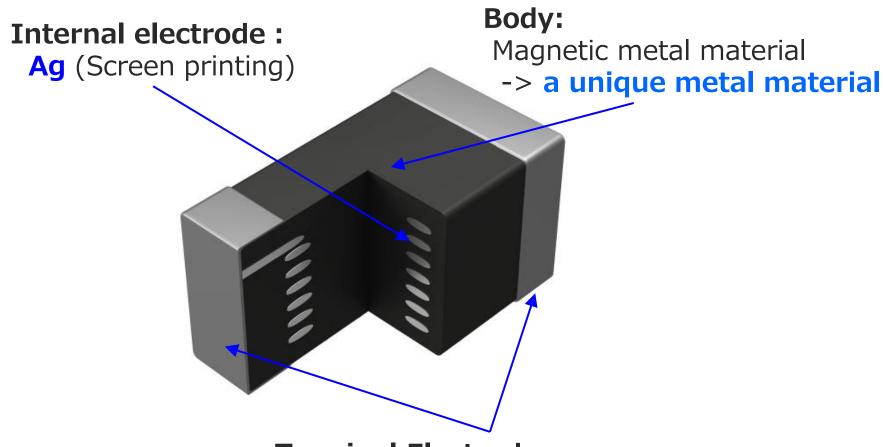


C). Capability of 2 in 1 (Mutually Coupled)





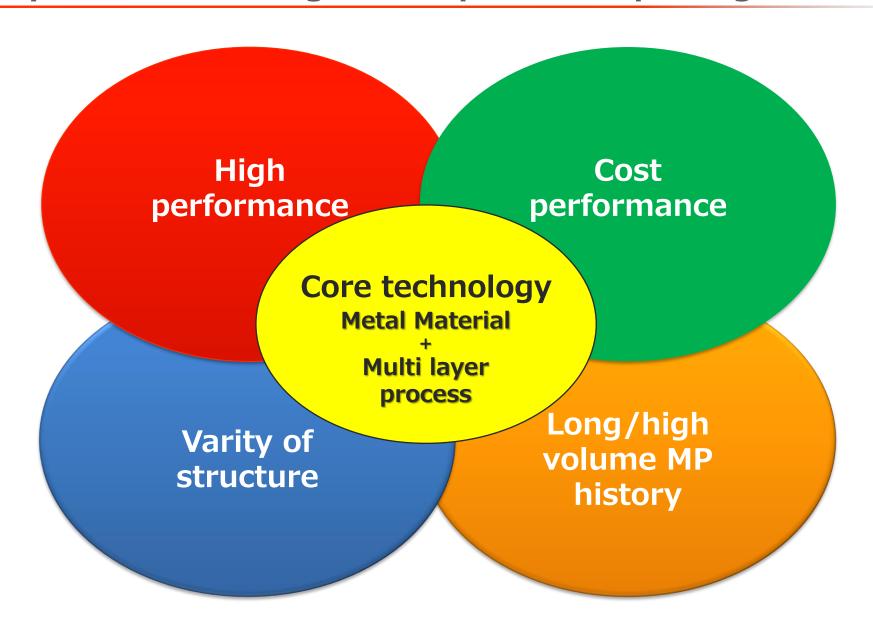
LSCN series Structure and Materials



Terminal Electrode:

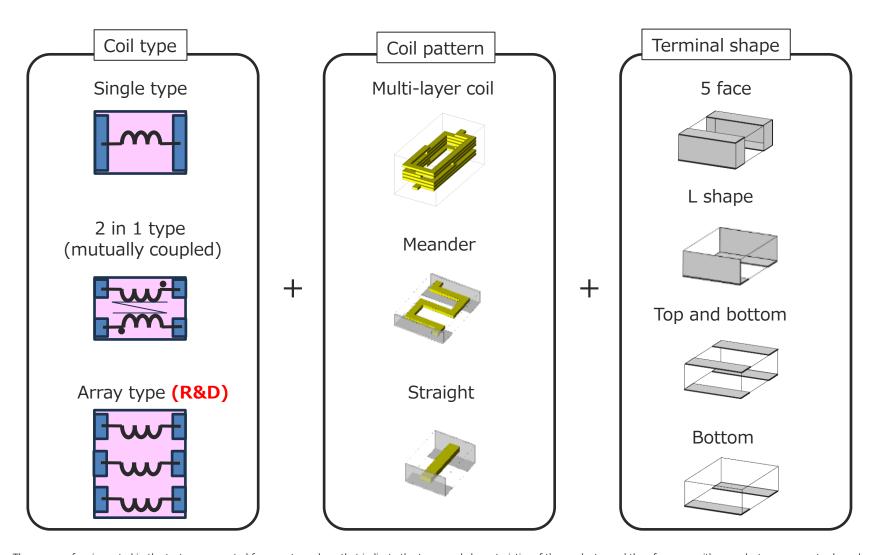
Ag base + Ni/Sn (or Cu) plating

Why LSCN series is good for processer package?



Variety of Structure

LSCN series has a high variety of structure because of multilayer process.



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Concept of Inductor and material design

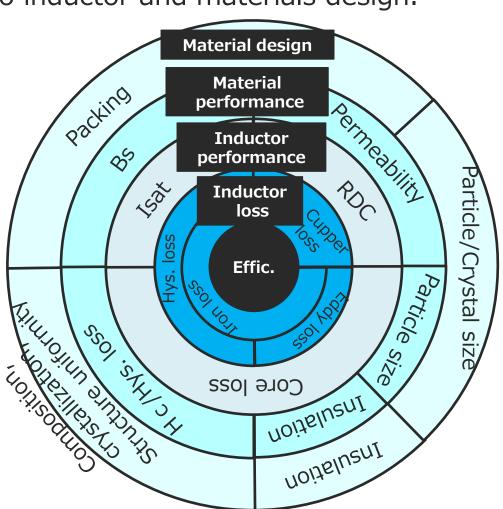
Target; To contribute to high efficiency power supplies.

Both of Static and Dynamic characteristics

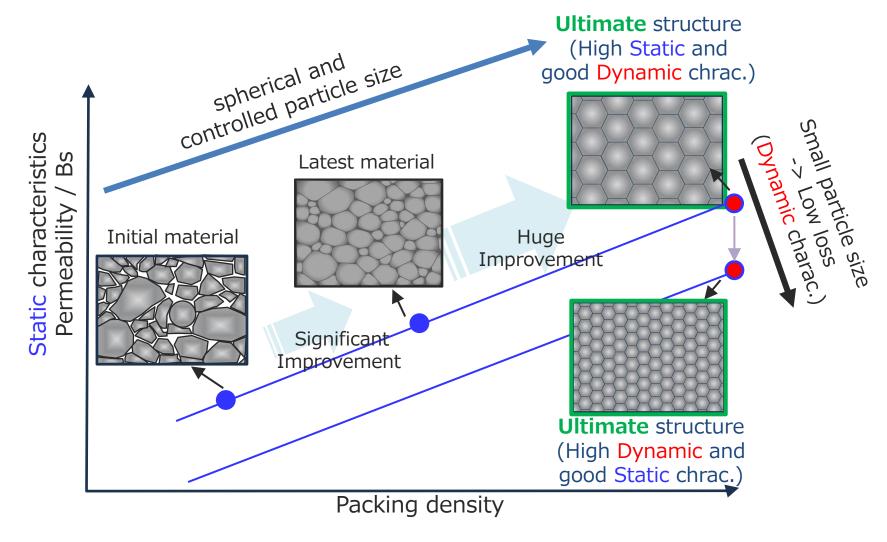
are considered to inductor and materials design.

Static characteristics (Inductance, RDC, Isat…)

Dynamic characteristics
Core loss



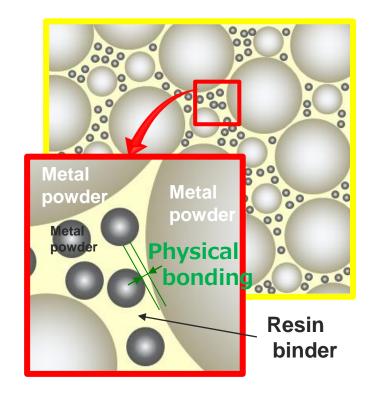
Both of High static and dynamic characteristics will be achieved by focusing on the improvement of packing density.



No resin binder -> High Packing density
Particle bonding; Oxide layer (chemical bonding)
-> High heat resistance and stability

LSCN series material (Thermal treated metal) Metal powder Oxide layer **Chemical** bonding Metal powder

General metal material (Metal composite)



Comparison of Inductor technologies for IVR



LSCN series has high performance and variety due to high packing density material and design flexibility.

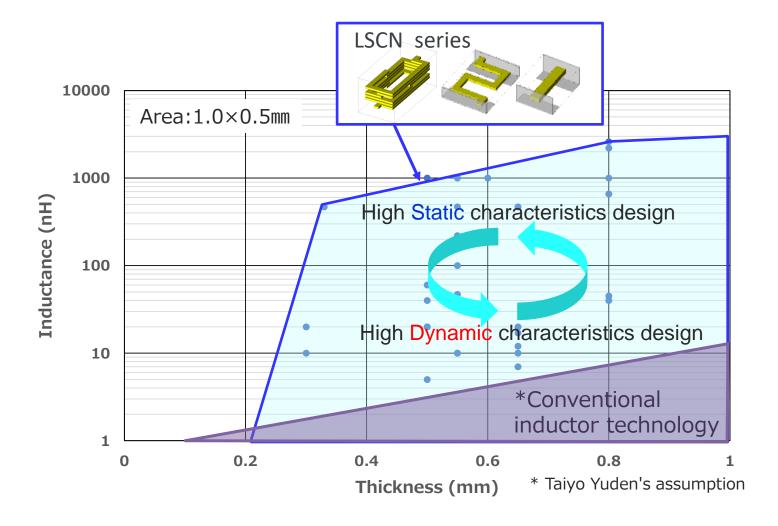
Inductor Technology		Conventional		LSCN series
		ACI*1)	Composite core*1)	Coil
		Source: Intel, ECTC 2020		
Magnetic Material	Packing Density	— (Non-Magnetic)	Low	High
Inductor specifications -	Inductance	1.2nH *1)	2.5nH *1)	40nH
	DC Resistance	7mΩ *1)	$12m\Omega$ *1)	8mΩ
	Imax	8A *1)	8A *1)	4.4A
	L/Rdc	171nH/Ω $^{*1)}$	208nH/Ω *1)	5000nH/Ω
	Area	2.0mm ^{2 *1)}	0.4mm ^{2 *1)}	0.5mm ²
	Current Density	4A/mm²	20A/mm ^{2*1)}	8.8A/mm ²
	Thickness	0.2mm	0.7mm	0.5mm

^{*1)} Source; Intel Corporation, 2021 IEEE 71st Electronic Components and Technology Conference (ECTC)

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Map of LSCN series Strong point

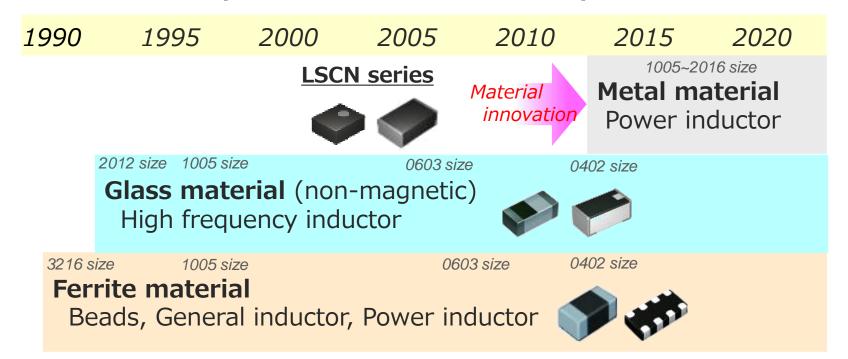
LSCN series can provide high performance over a wide range (inductance x thickness) due to variety of structure and material.



TAIYO YUDEN's multilayer inductors; more than 30 years. Metal inductor LSCN series; based on common technologies and has a history of 10 years.

- -> Stable mass production, high productivity
- -> High cost performance

History of TAIYO YUDEN's multi layer inductors



Summary

- ✓ Proposal of Inductor for IVR with good performance and cost competitiveness.
- ✓ TAIYO YUDEN LSCN series is good for IVR in the following points.
 - 1. A unique product, metal material × multi layer process,
 - -> variety of structure and high performance.
 - 2. based on multi layer inductor technology with a 30 years history
 - -> Stable mass production, High cost performance.

Please contact us below

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